

CLAIMS

1. A heat-dissipating member,
which comprises a thermoplastic resin composition
5 containing a thermoplastic resin and a thermally conductive
fine particle and not containing a compound having a
melting temperature in the range of 40 to 80°C,
at 23°C, a storage modulus at 0.1 Hz being 50,000 Pa
or larger and the member remains finite in shape, and
10 in the range of 50 to 80°C, a storage modulus at 0.1
Hz being 400 to 50,000 Pa and the member being indefinite
in shape, and
at 100°C, a storage modulus at 0.1 Hz being 5,000 Pa
or smaller and the member being indefinite in shape.
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2. The heat-dissipating member according to claim 1,
wherein the thermoplastic resin is a styrene block
copolymer and/or a butyl-rubber resin.
- 20 3. The heat-dissipating member according to claim 2,
wherein the styrene block copolymer is a styrene-
isoprene-styrene block copolymer having the proportion of
diblock of styrene-isoprene being 50% by weight or larger
and the content of styrene being 25% by weight or smaller.
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4. The heat-dissipating member according to claim 1,
2 or 3,
wherein the thermoplastic resin composition mainly
contains an aromatic thermoplastic resin being solid at
30 23°C and further contains a xylene resin having viscosity
at 23°C.
5. A joined structure obtainable by joining a heat
sink to a heat generating element with the heat-dissipating
35 member according to claim 1, 2, 3 or 4,

wherein thickness of the heat-dissipating member may be reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

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6. A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 1, 2, 3 or 4,

10 wherein thickness of the heat-dissipating member has already been reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.